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# **MA3S132DG, MA3S132EG**

## Silicon epitaxial planar type

### For switching circuits

#### ■ Features

- Short reverse recovery time t<sub>rr</sub>
- Small terminal capacitance C<sub>t</sub>
- Two isolated elements contained in one package, allowing highdensity mounting

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Reverse voltage		V <sub>R</sub>	80	V	
Maximum peak reverse voltage		$V_{RM}$	80	V	
Forward current	Single	$I_{\mathrm{F}}$	100	mA	
	Double		150		
Peak forward	Single	$I_{FM}$	225	mA	
current	Double		340		
Non-repetitive peak	Single	$I_{FSM}$	500	mA	
forward surge current *	Double		750		
Junction temperature		T <sub>j</sub>	150	°C	
Storage temperature		T <sub>stg</sub>	-55 to +150	c°C	

Note) \*: t = 1 s

#### Package

- Code
  - SSMini3-F3

 Pin Name MA3S132DG

MA3S132EG

1: Cathode 1 2: Cathode 2 1: Anode 1 2: Anode 2

3: Anode

3: Cathode

## Marking Symbol

MA3S132DG: MO MA3S132EG: MU

#### Internal Connection



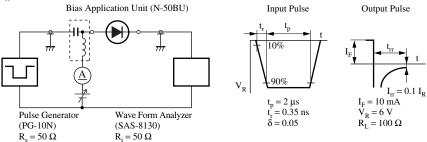


## ■ Electrical Characteristics T<sub>a</sub> = 25°C ± 3°C

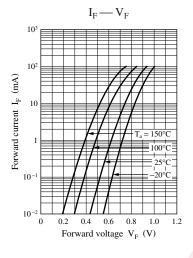
Parameter		Symbol	Conditions	Min	Тур	Max	Unit	
Forward voltage		$V_{\rm F}$	$I_F = 100 \text{ mA}$		<b>O</b> -	1.2	V	
Reverse voltage		$V_R$	$I_R = 100 \mu A$	80			V	
Reverse current		$I_R$	V <sub>R</sub> = 75 V			100	nA	
Terminal capacitance	MA3S132DG	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$			15	pF	
	MA3S132EG		1, 1011			2		
Reverse recovery time *	MA3S132DG	t <sub>rr</sub>	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			10	ns	
No.	MA3S132EG		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$			3		

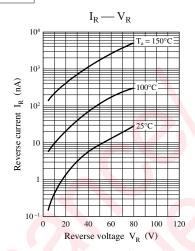
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

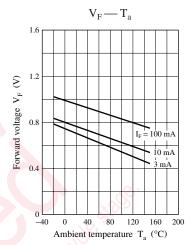
- 2. Absolute frequency of input and output is 100 MHz.
- 3. \*: t<sub>rr</sub> measurement circuit

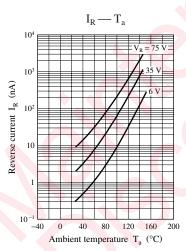


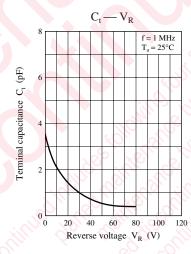
### Characteristics charts of MA3S132DG

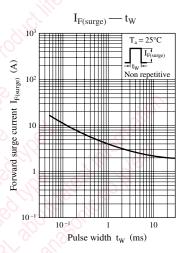








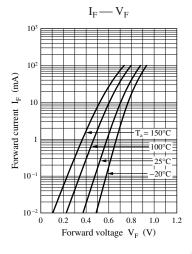


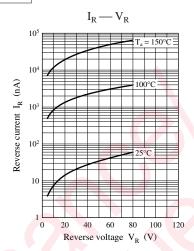


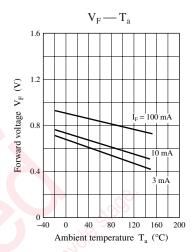
3 SKF00083AED

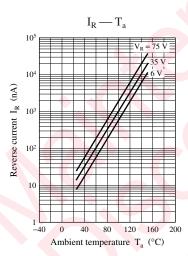
## **Panasonic**

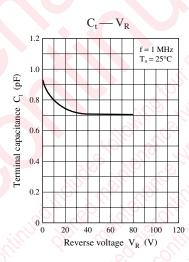
### Characteristics charts of MA3S132EG

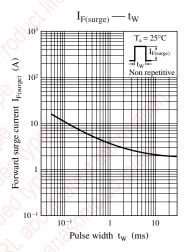






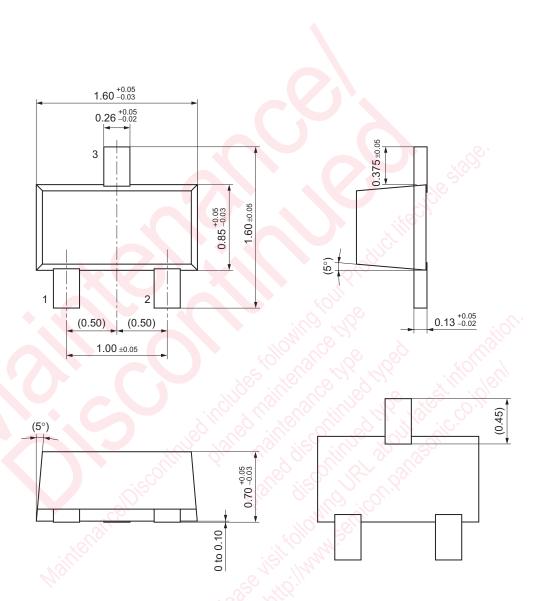






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SSMini3-F3 Unit: mm



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